

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3406377

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WAN-YU LEE	08/15/2013
CHUN-HAO TSENG	08/16/2013
JUI HSIEH LAI	08/15/2013
TIEN-YU HUANG	08/15/2013
YING-HAO KUO	08/16/2013
KUO-CHUNG YEE	08/16/2013
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14745701
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	T5057-921A
NAME OF SUBMITTER:	RANDY A. NORANBROCK
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	06/22/2015

Total Attachments: 2

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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|-------------------|------------------|
| 1) Wan-Yu LEE | 4) Tien-Yu HUANG |
| 2) Chun-Hao TSENG | 5) Ying-Hao KUO |
| 3) Jui Hsieh LAI | 6) Kuo-Chung YEE |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MANUFACTURE INCLUDING SUBSTRATE AND PACKAGE STRUCTURE OF OPTICAL CHIP

(a) for which an application for United States Letters Patent was filed on August 30, 2013, and identified by United States Patent Application No. 14/015,757; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Wan Yu Lee
Name: Wan-Yu LEE

2013-8-15
Date:

2) Chun-Hao Tseng
Name: Chun-Hao TSENG

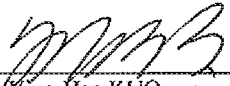
2013. 8. 16.
Date:

3) Jui Hsieh LAI
Name: Jui Hsieh LAI

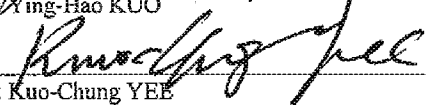
2013. 8. 15
Date:

4) Jui Hsieh LAI. Tien-Yu HUANG
Name: Tien-Yu HUANG

2013-8-15
Date:

5) 
Name: Ying-Hao KUO

2013.8.16
Date:

6) 
Name: Kuo-Chung YEE

2013.8.16
Date: